

Features

- ❖ Glass passivated
- ❖ High maximum operating temperature
- ❖ Low leakage current
- ❖ Excellent stability
- ❖ Guaranteed avalanche energy absorption capability
- ❖ Available in ammo-pack.

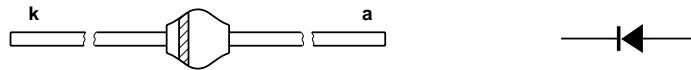


Fig.1 Simplified outline (SOD57) and symbol.

Applications

Rugged glass SOD57 package, using a high temperature alloyed construction. This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage BYV36A		–	200	V
	BYV36B			400	V
	BYV36C			600	V
	BYV36D			800	V
	BYV36E			1000	V
	BYV36F			1200	V
	BYV36G			1400	V
V_R	continuous reverse voltage BYV36A		–	200	V
	BYV36B			400	V
	BYV36C			600	V
	BYV36D			800	V
	BYV36E			1000	V
	BYV36F			1200	V
	BYV36G			1400	V
$I_{F(AV)}$	average forward current BYV36A to C	$T_{tp} = 60^\circ\text{C}$; lead length = 10 mm; see Figs 2; 3 and 4 averaged over any 20 ms period; see also Figs 14; 15 and 16	–	1.6	A
	BYV36D and E			1.5	A
	BYV36F and G			1.5	A
$I_{F(AV)}$	average forward current BYV36A to C	$T_{amb} = 60^\circ\text{C}$; PCB mounting (see Fig.25); see Figs 5; 6 and 7 averaged over any 20 ms period; see also Figs 14; 15 and 16	–	0.87	A
	BYV36D and E			0.81	A
	BYV36F and G			0.81	A



BYV36 Series

Fast soft-recovery Controlled Avalanche Rectifiers

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{FRM}	repetitive peak forward current BYV36A to C	$T_{tp} = 60^\circ\text{C}$; see Figs 8; 9 and 10	–	18	A
	BYV36D and E				
	BYV36F and G				
I_{FRM}	repetitive peak forward current BYV36A to C	$T_{amb} = 60^\circ\text{C}$; see Figs 11; 12 and 13	–	9	A
	BYV36D and E				
	BYV36F and G				
I_{FSM}	non-repetitive peak forward current	$t = 10 \text{ ms}$ half sine wave; $T_j = T_{j\max}$ prior to surge; $V_R = V_{RRM\max}$	–	30	A
E_{RSM}	non-repetitive peak reverse avalanche energy	$L = 120 \text{ mH}$; $T_j = T_{j\max}$ prior to surge; inductive load switched off	–	10	mJ
T_{stg}	storage temperature		–65	+175	°C
T_j	junction temperature	see Figs 17 and 18	–65	+175	°C

ELECTRICAL CHARACTERISTICS

$T_j = 25^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	forward voltage BYV36A to C	$I_F = 1 \text{ A}$; $T_j = T_{j\max}$; see Figs 19; 20 and 21	–	–	1.00	V
	BYV36D and E					
	BYV36F and G					
V_F	forward voltage BYV36A to C	$I_F = 1 \text{ A}$; see Figs 19; 20 and 21	–	–	1.35	V
	BYV36D and E					
	BYV36F and G					
$V_{(BR)R}$	reverse avalanche breakdown voltage BYV36A	$I_R = 0.1 \text{ mA}$	300 500 700 900 1100 1300 1500	–	–	V
	BYV36B					
	BYV36C					
	BYV36D					
	BYV36E					
	BYV36F					
	BYV36G					
I_R	reverse current	$V_R = V_{RRM\max}$; see Fig.22	–	–	5	μA
		$V_R = V_{RRM\max}$; $T_j = 165^\circ\text{C}$; see Fig.22	–	–	150	μA



BYV36 Series

Fast soft-recovery Controlled Avalanche Rectifiers

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t_{rr}	reverse recovery time BYV36A to C BYV36D and E BYV36F and G	when switched from $I_F = 0.5 \text{ A}$ to $I_R = 1 \text{ A}$; measured at $I_R = 0.25 \text{ A}$; see Fig. 26	—	—	100	ns
C_d	diode capacitance BYV36A to C BYV36D and E BYV36F and G	$f = 1 \text{ MHz}$; $V_R = 0 \text{ V}$; see Figs 23 and 24	—	45	—	pF
$\left \frac{dI_R}{dt} \right $	maximum slope of reverse recovery current BYV36A to C BYV36D and E BYV36F and G	when switched from $I_F = 1 \text{ A}$ to $V_R \geq 30 \text{ V}$ and $dI_F/dt = -1 \text{ A}/\mu\text{s}$; see Fig.27	—	40	—	pF
			—	35	—	pF
			—	—	7	A/ μs
			—	—	6	A/ μs
			—	—	5	A/ μs

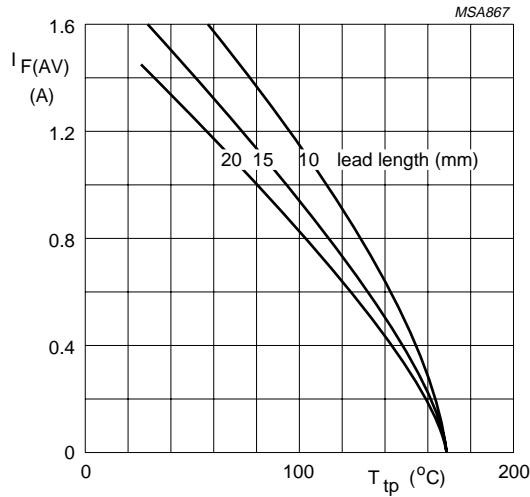
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th j\text{-tp}}$	thermal resistance from junction to tie-point	lead length = 10 mm	46	K/W
$R_{th j\text{-a}}$	thermal resistance from junction to ambient	note 1	100	K/W

Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer $\geq 40 \mu\text{m}$, see Fig.25.
For more information please refer to the "General Part of associated Handbook".

GRAPHICAL DATA

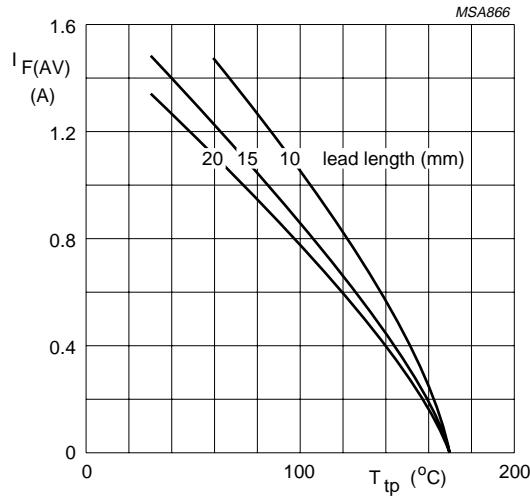


BYV36A to C

$a = 1.42; V_R = V_{RRMmax}; \delta = 0.5.$

Switched mode application.

Fig.2 Maximum average forward current as a function of tie-point temperature (including losses due to reverse leakage).

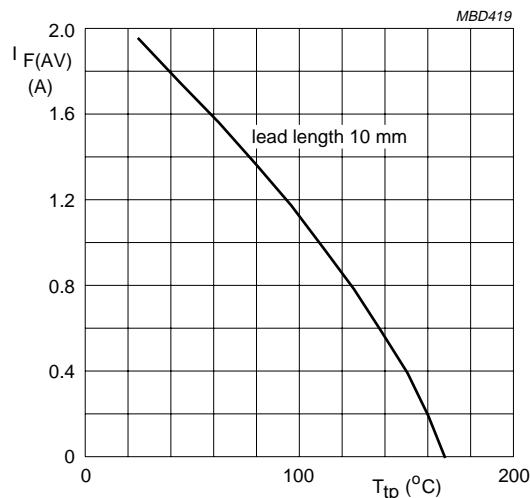


BYV36D and E

$a = 1.42; V_R = V_{RRMmax}; \delta = 0.5.$

Switched mode application.

Fig.3 Maximum average forward current as a function of tie-point temperature (including losses due to reverse leakage).

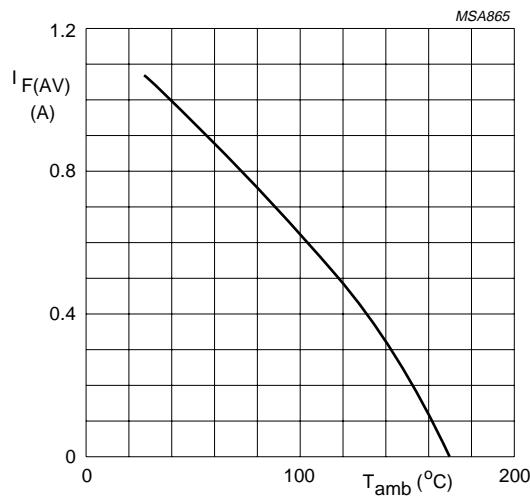


BYV36F and G

$a = 1.42; V_R = V_{RRMmax}; \delta = 0.5.$

Switched mode application.

Fig.4 Maximum average forward current as a function of tie-point temperature (including losses due to reverse leakage).



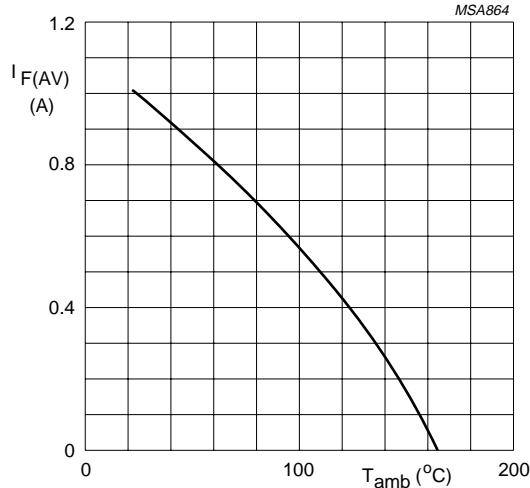
BYV36A to C

$a = 1.42; V_R = V_{RRMmax}; \delta = 0.5.$

Device mounted as shown in Fig.25.

Switched mode application.

Fig.5 Maximum average forward current as a function of ambient temperature (including losses due to reverse leakage).

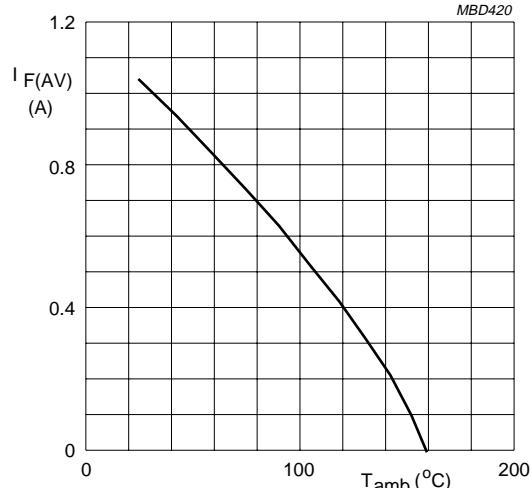

BYV36D and E

$a = 1.42$; $V_R = V_{RRMmax}$; $\delta = 0.5$.

Device mounted as shown in Fig.25.

Switched mode application.

Fig.6 Maximum average forward current as a function of ambient temperature (including losses due to reverse leakage).

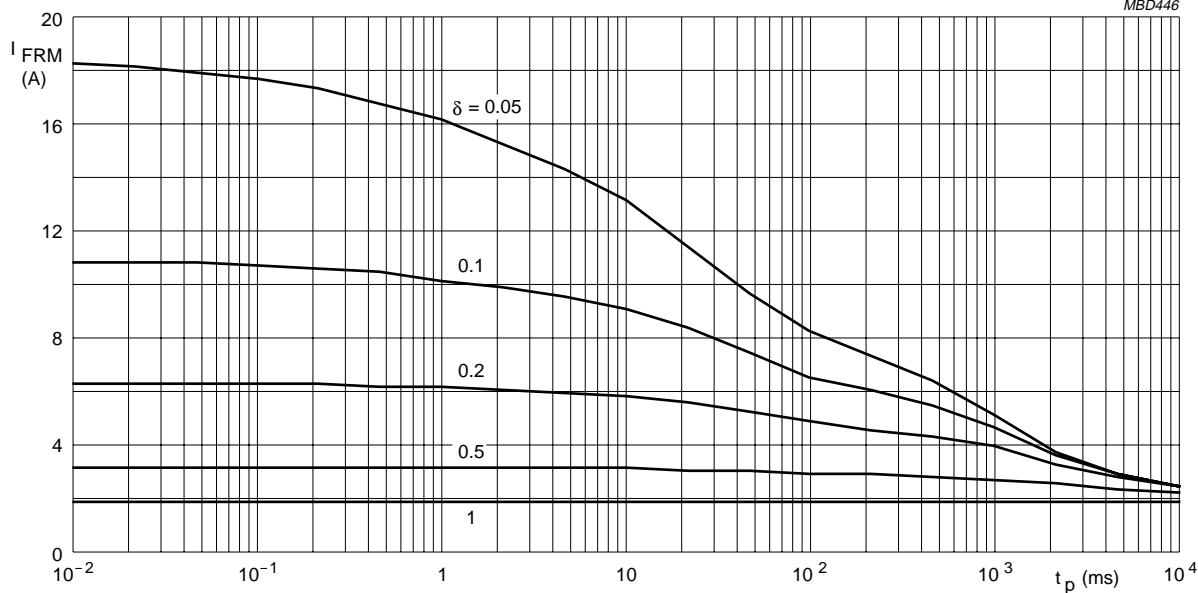

BYV36F and G

$a = 1.42$; $V_R = V_{RRMmax}$; $\delta = 0.5$.

Device mounted as shown in Fig.25.

Switched mode application.

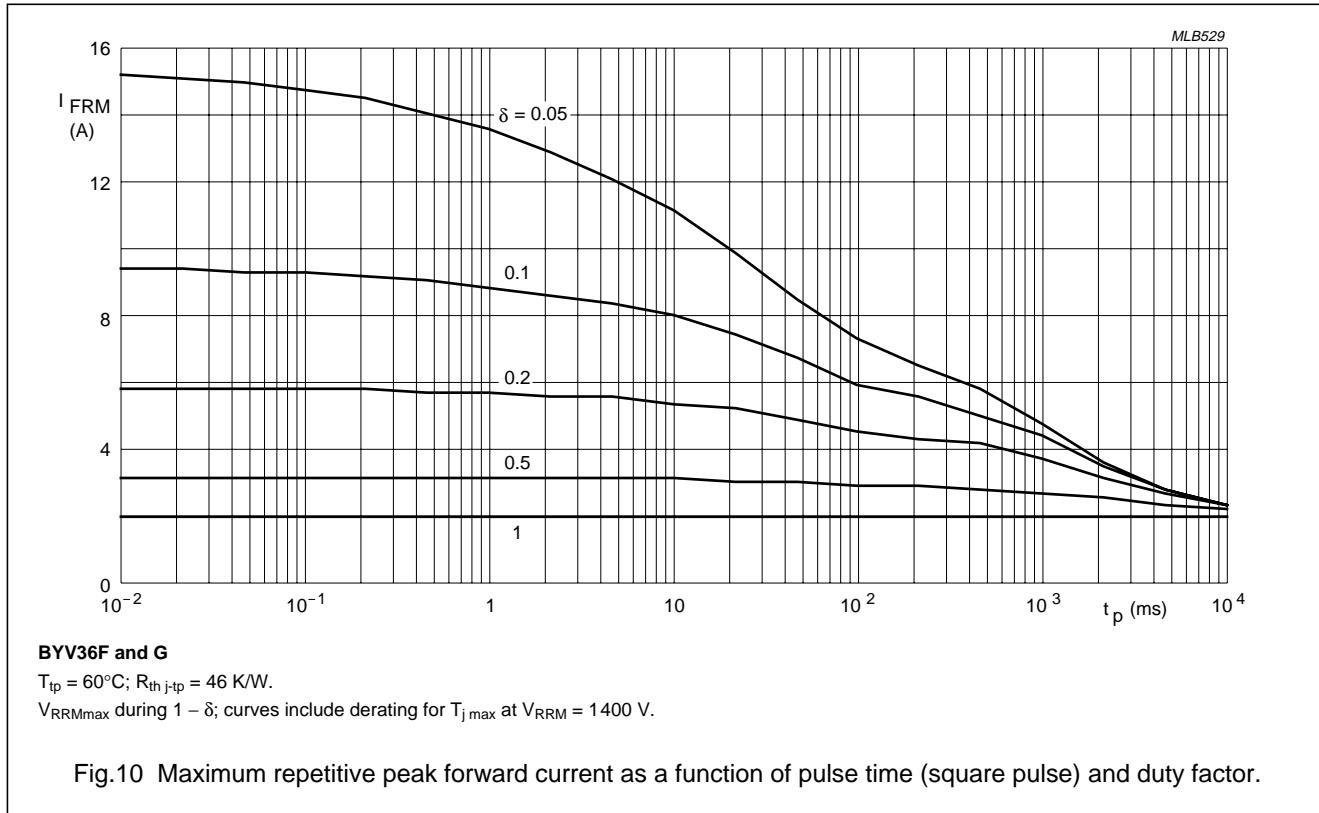
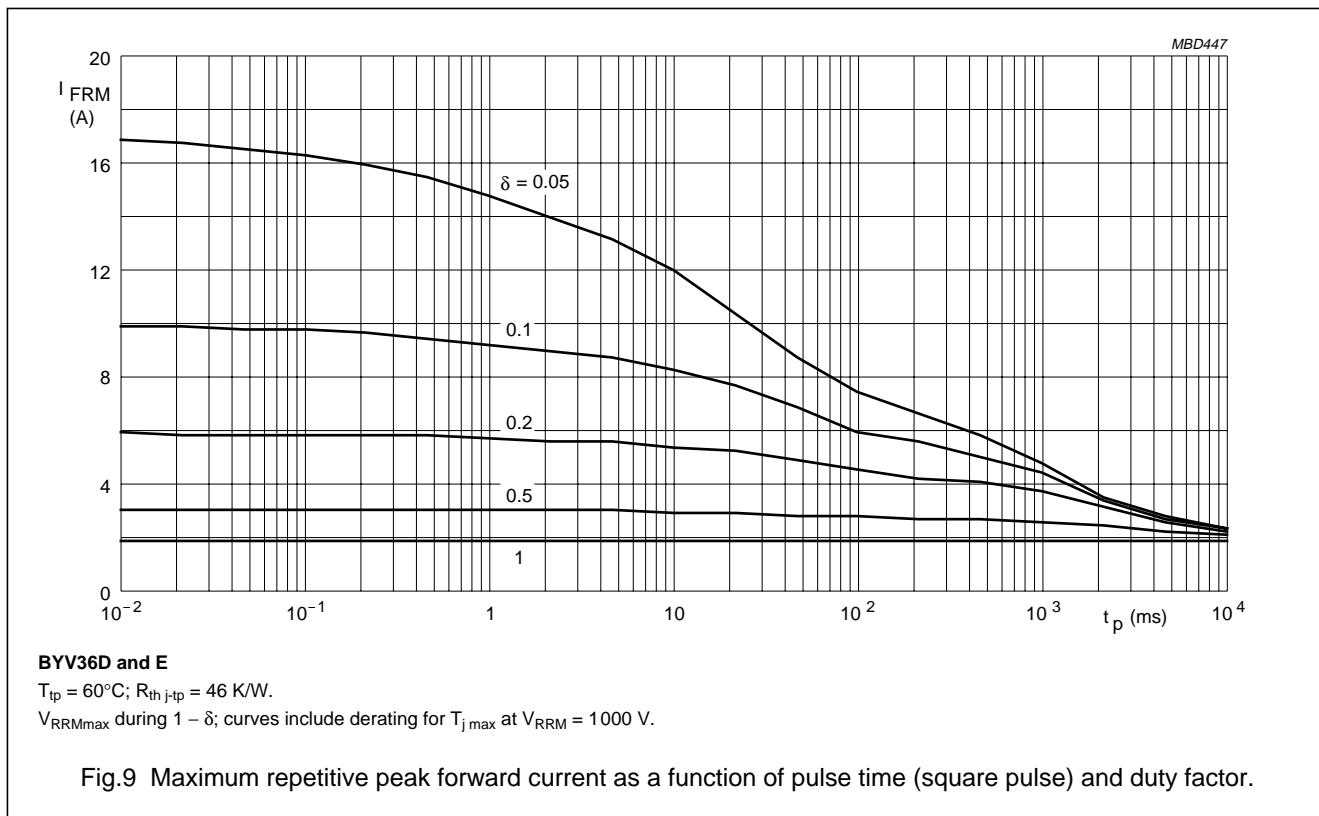
Fig.7 Maximum average forward current as a function of ambient temperature (including losses due to reverse leakage).

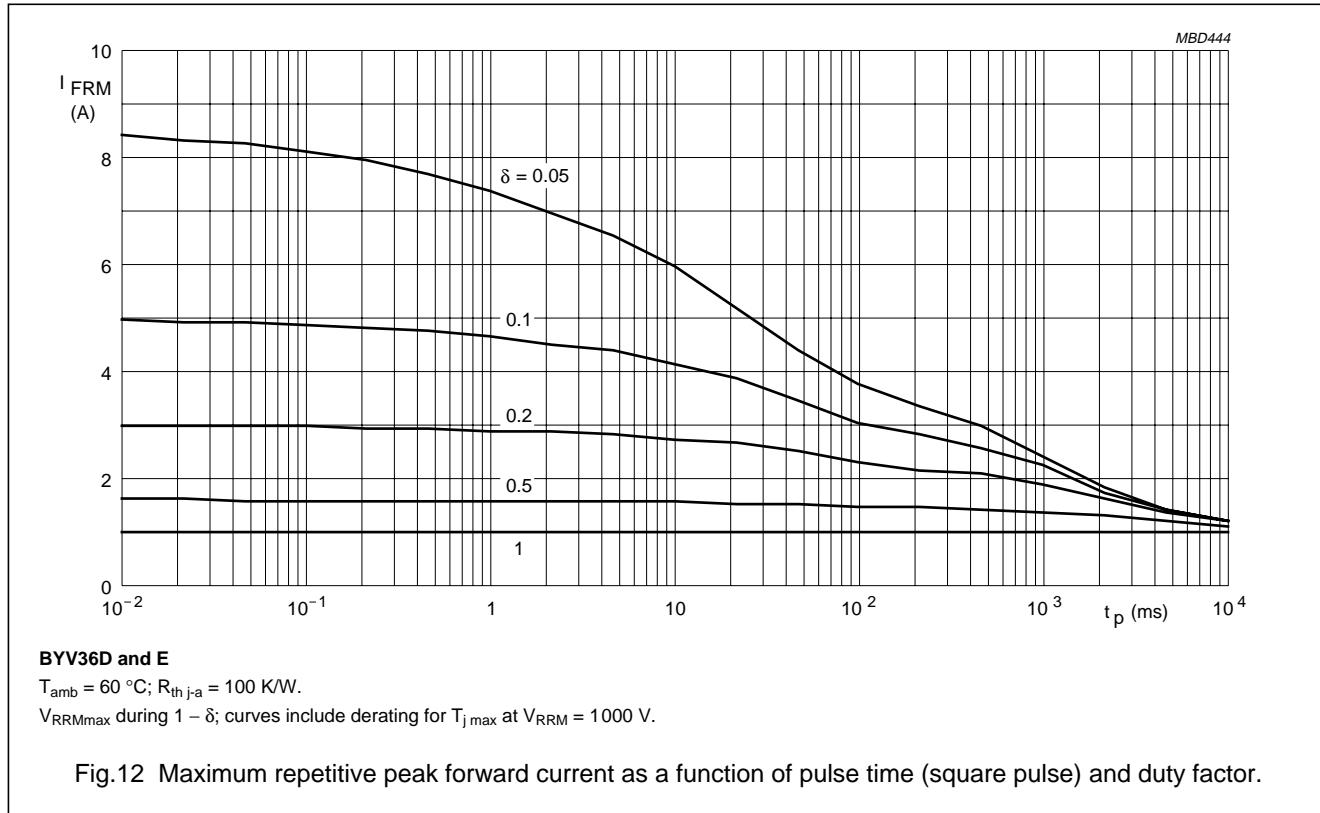
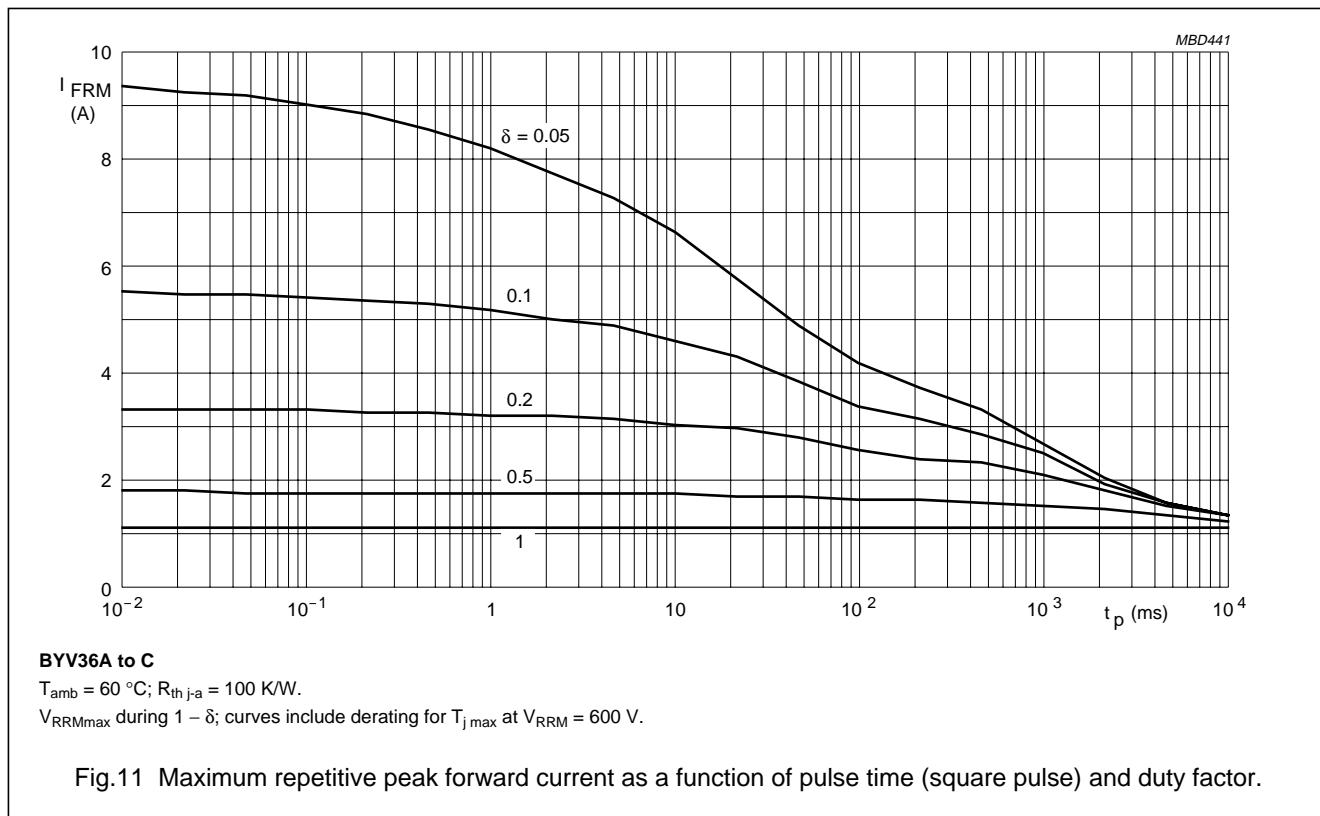

BYV36A to C

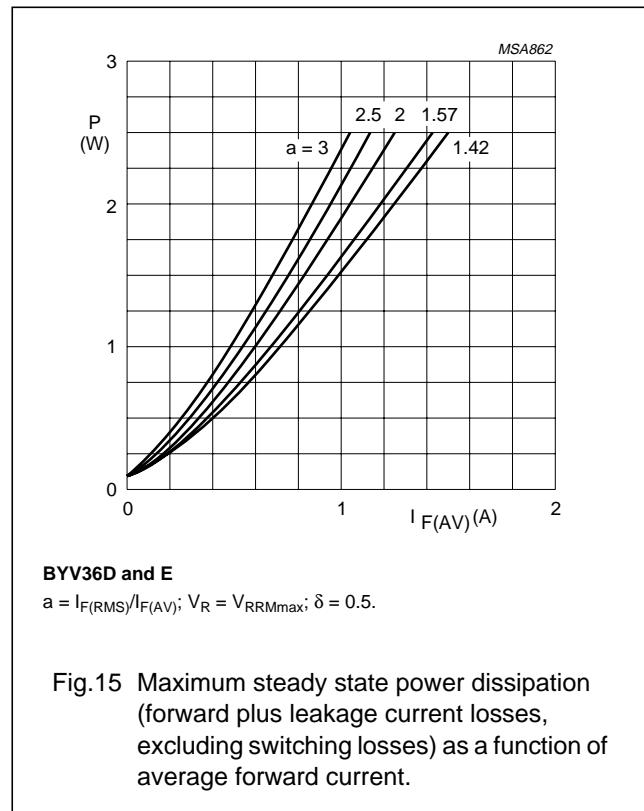
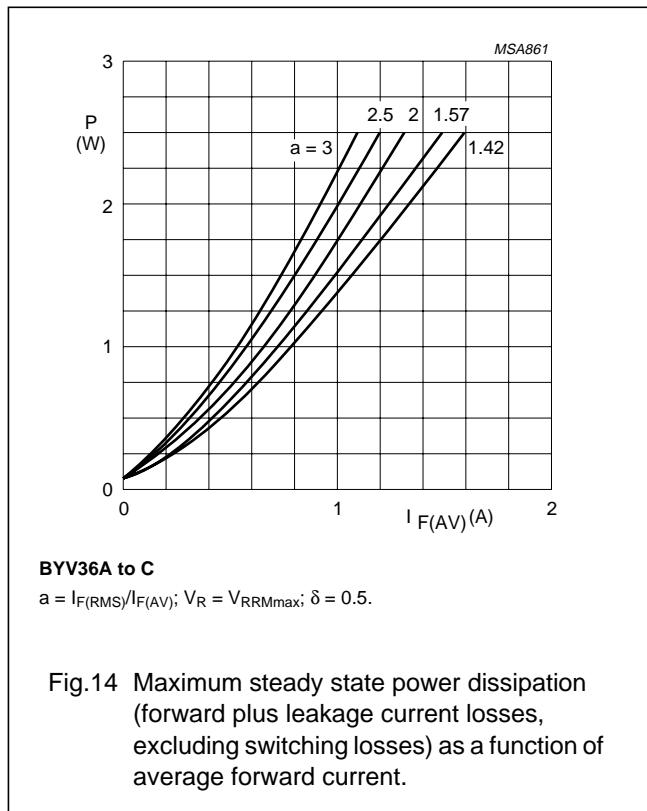
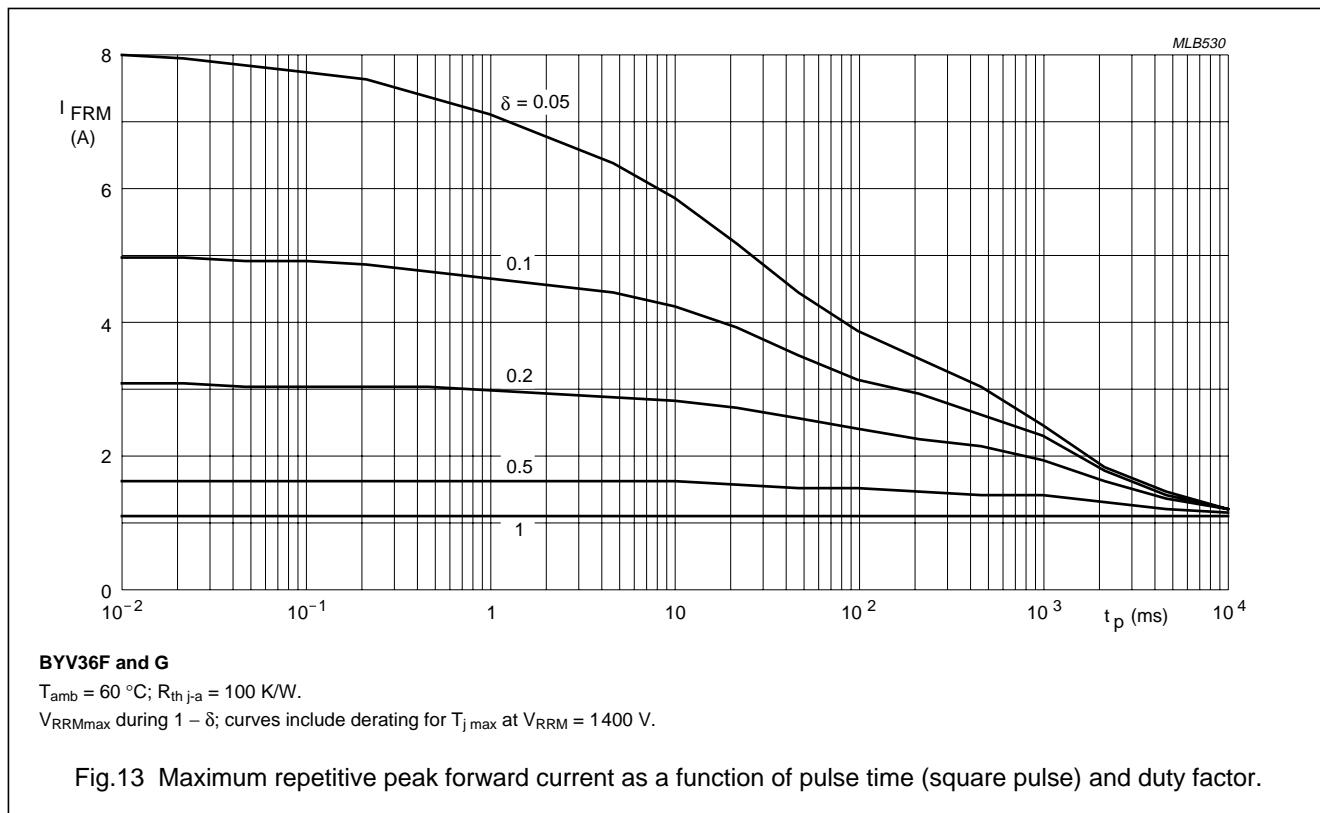
$T_{tp} = 60^\circ\text{C}$; $R_{th,j,fp} = 46 \text{ K/W}$.

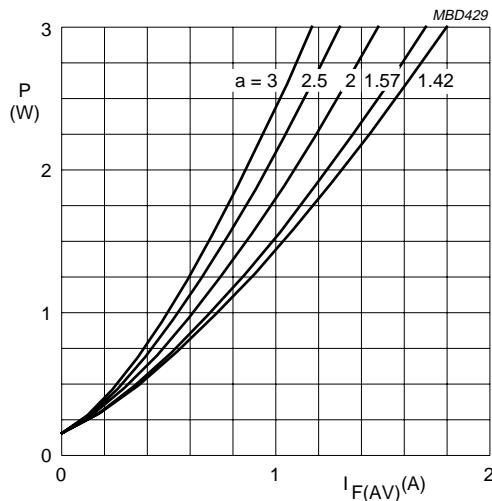
V_{RRMmax} during $1 - \delta$; curves include derating for $T_{j,max}$ at $V_{RRM} = 600 \text{ V}$.

Fig.8 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.





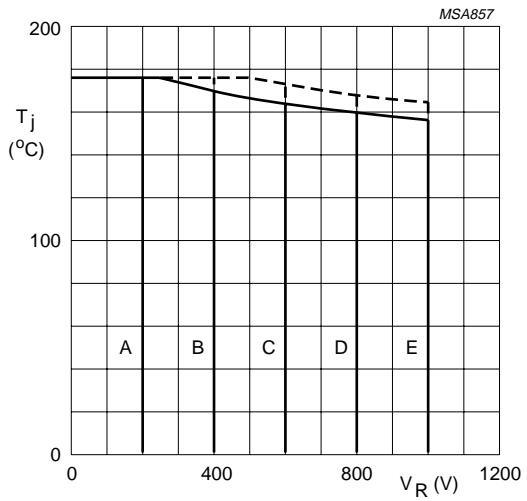




BYV36F and G

$a = I_{F(\text{RMS})}/I_{F(\text{AV})}; V_R = V_{\text{RRMmax}}; \delta = 0.5$.

Fig.16 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

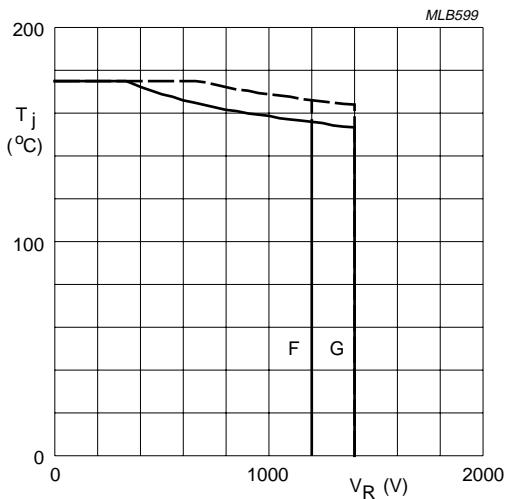


BYV36A to E

Solid line = V_R .

Dotted line = $V_{\text{RRM}}; \delta = 0.5$.

Fig.17 Maximum permissible junction temperature as a function of reverse voltage.

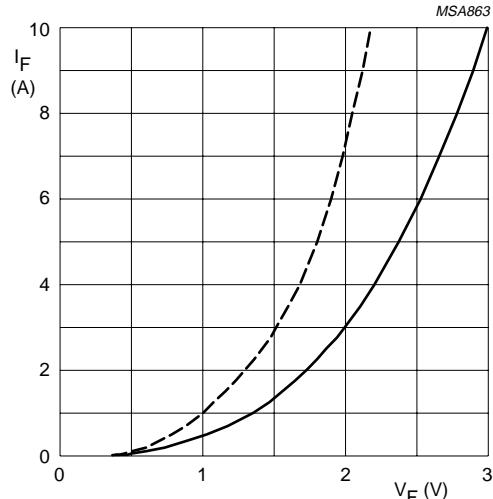


BYV36F and G

Solid line = V_R .

Dotted line = $V_{\text{RRM}}; \delta = 0.5$.

Fig.18 Maximum permissible junction temperature as a function of reverse voltage.

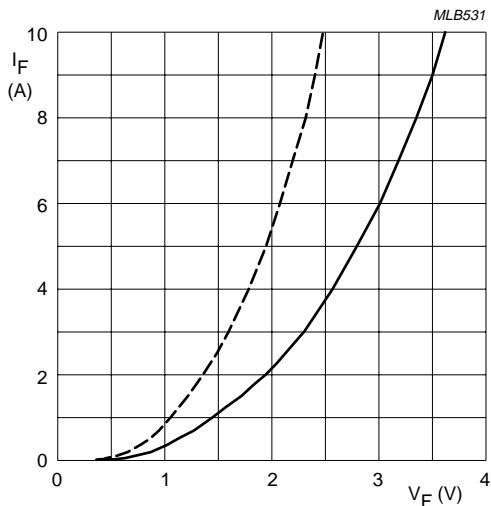


BYV36A to C

Dotted line: $T_j = 175^\circ\text{C}$.

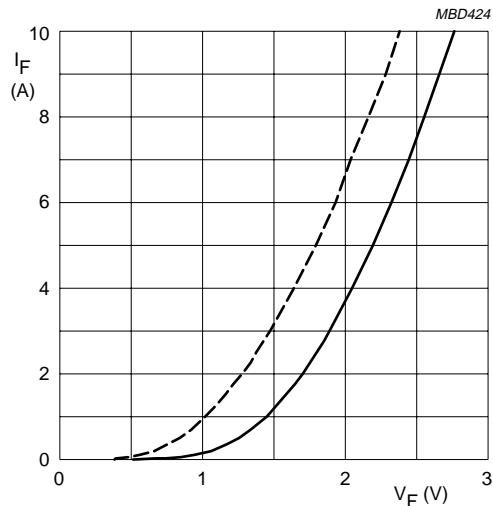
Solid line: $T_j = 25^\circ\text{C}$.

Fig.19 Forward current as a function of forward voltage; maximum values.


BYV36D and E

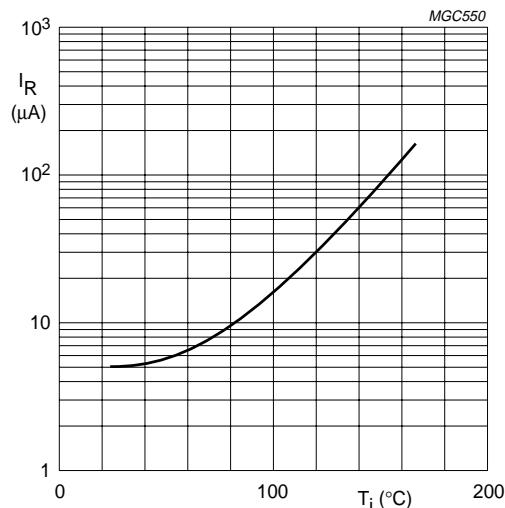
Dotted line: $T_j = 175^\circ\text{C}$.
 Solid line: $T_j = 25^\circ\text{C}$.

Fig.20 Forward current as a function of forward voltage; maximum values.


BYV36F and G

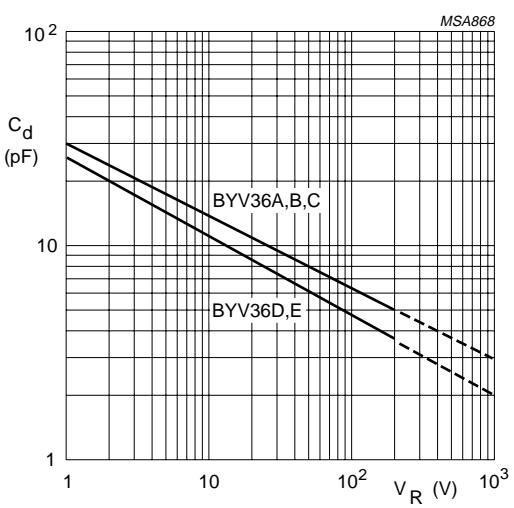
Dotted line: $T_j = 175^\circ\text{C}$.
 Solid line: $T_j = 25^\circ\text{C}$.

Fig.21 Forward current as a function of forward voltage; maximum values.



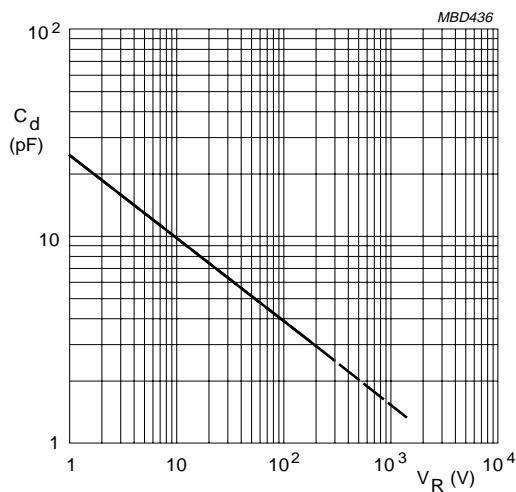
$V_R = V_{RRMmax}$.

Fig.22 Reverse current as a function of junction temperature; maximum values.


BYV36A to E.

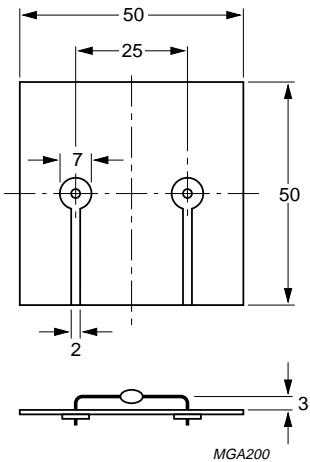
$f = 1 \text{ MHz}$; $T_j = 25^\circ\text{C}$.

Fig.23 Diode capacitance as a function of reverse voltage, typical values.



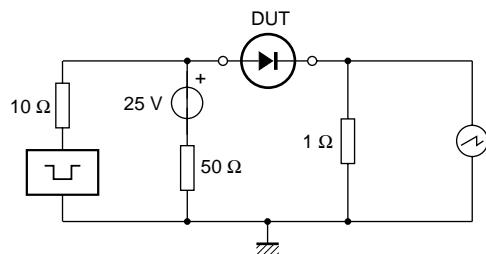
BYV36F and G.
 $f = 1 \text{ MHz}$; $T_j = 25^\circ\text{C}$.

Fig.24 Diode capacitance as a function of reverse voltage, typical values.



Dimensions in mm.

Fig.25 Device mounted on a printed-circuit board.



Input impedance oscilloscope: $1 \text{ M}\Omega$, 22 pF ; $t_r \leq 7 \text{ ns}$.
Source impedance: 50Ω ; $t_r \leq 15 \text{ ns}$.

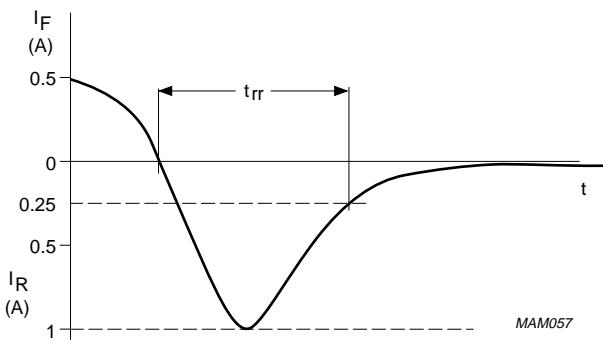
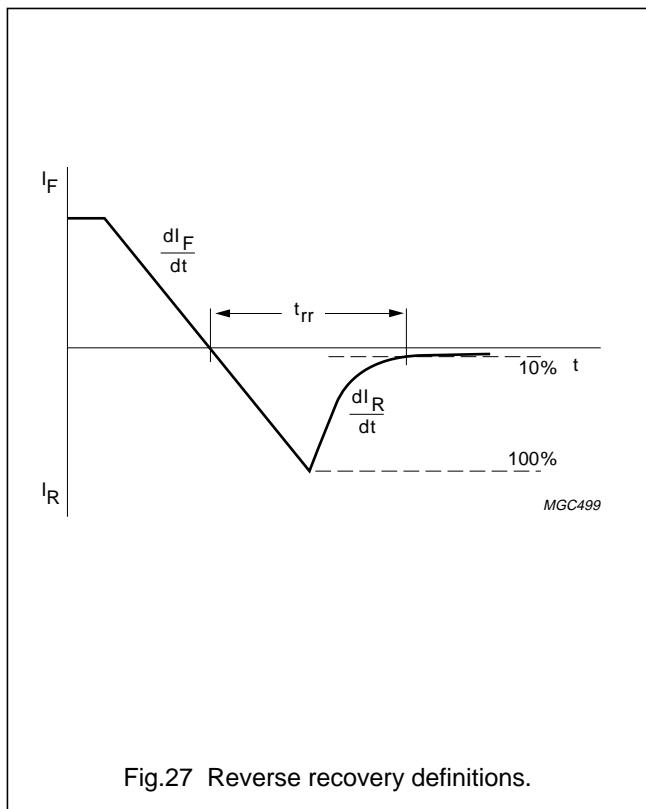


Fig.26 Test circuit and reverse recovery time waveform and definition.



PACKAGE OUTLINE

